

## PROTECTION PRODUCTS

### Absolute Maximum Rating

| Rating   | Symbol    | Value            | Units |
|--|-----------|------------------|-------|
| Peak Pulse Power ( $t_p = 8/20\mu s$ )                         | $P_{pk}$  | 100              | Watts |
| Maximum Peak Pulse Current ( $t_p = 8/20\mu s$ )               | $I_{pp}$  | 7                | Amps  |
| ESD per IEC 61000-4-2 (Air)<br>ESD per IEC 61000-4-2 (Contact) | $V_{pp}$  | +/- 20<br>+/- 12 | kV    |
| Lead Soldering Temperature                                     | $T_L$     | 260 (10 sec.)    | °C    |
| Operating Temperature  | $T_J$     | -55 to +125      | °C    |
| Storage Temperature  | $T_{STG}$ | -55 to +150      | °C    |

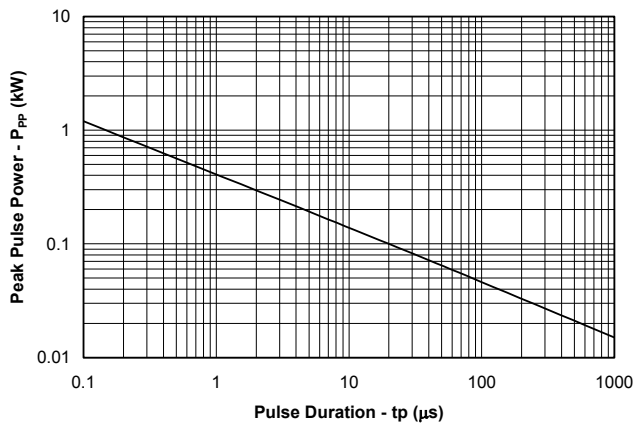
### Electrical Characteristics (T=25°C)

| Parameter                 | Symbol    | Conditions                                       | Minimum | Typical | Maximum | Units   |
|---------------------------|-----------|--|---------|---------|---------|---------|
| Reverse Stand-Off Voltage | $V_{RWM}$ |  |         |         | 5       | V       |
| Reverse Breakdown Voltage | $V_{BR}$  | $I_t = 1mA$                                      | 6       |         |         | V       |
| Reverse Leakage Current   | $I_R$     | $V_{RWM} = 5V, T=25^\circ C$                     |         |         | 1       | $\mu A$ |
| Reverse Leakage Current   | $I_R$     | $V_{RWM} = 3V, T=25^\circ C$                     |         |         | 0.500   | $\mu A$ |
| Forward Voltage           | $V_F$     | $I_F = 10mA$                                     |         | 0.80    |         | V       |
| Clamping Voltage          | $V_C$     | $I_{pp} = 1A, t_p = 8/20\mu s$                   |         |         | 10      | V       |
| Clamping Voltage          | $V_C$     | $I_{pp} = 7A, t_p = 8/20\mu s$                   |         |         | 12      | V       |
| Junction Capacitance      | $C_j$     | Between I/O Pins and Gnd<br>$V_R = 0V, f = 1MHz$ |         | 60      | 75      | pF      |

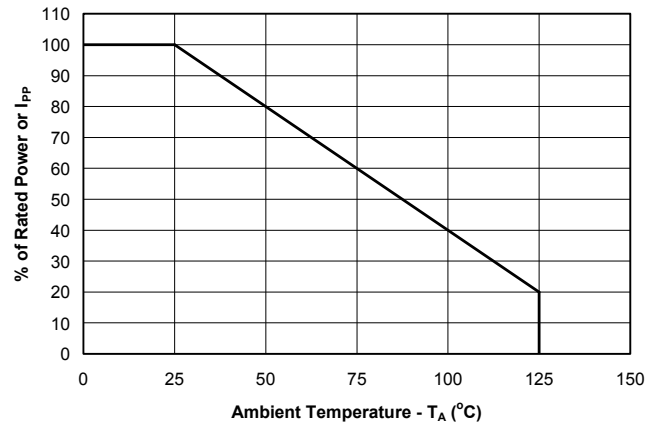
# PROTECTION PRODUCTS

## Typical Characteristics

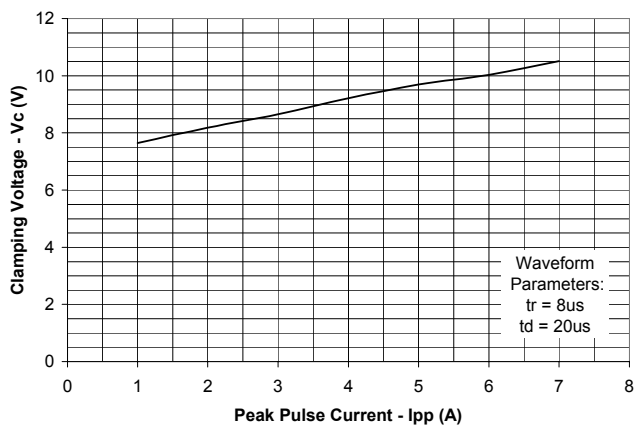
### Non-Repetitive Peak Pulse Power vs. Pulse Time



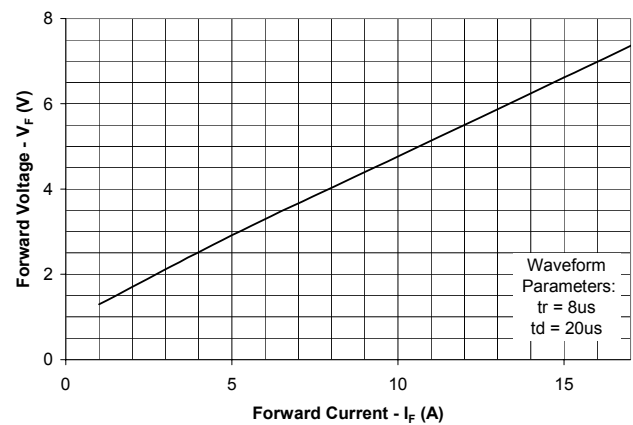
### Power Derating Curve



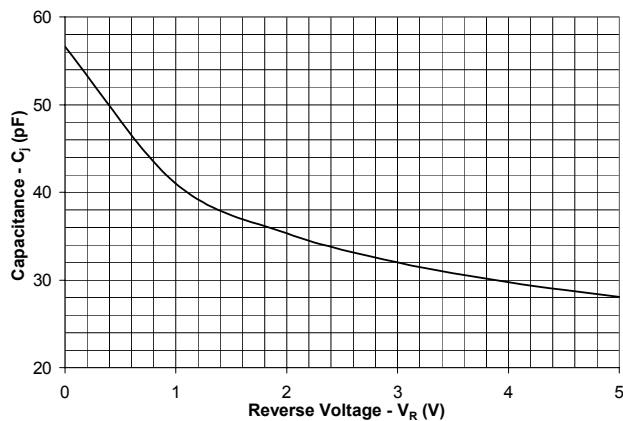
### Clamping Voltage vs. Peak Pulse Current



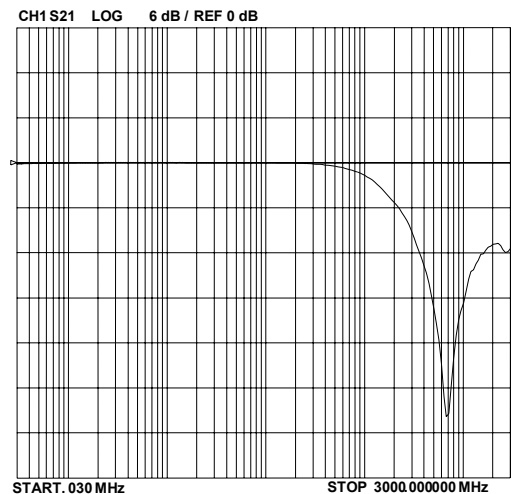
### Forward Voltage vs. Forward Current



### Junction Capacitance vs. Reverse Voltage



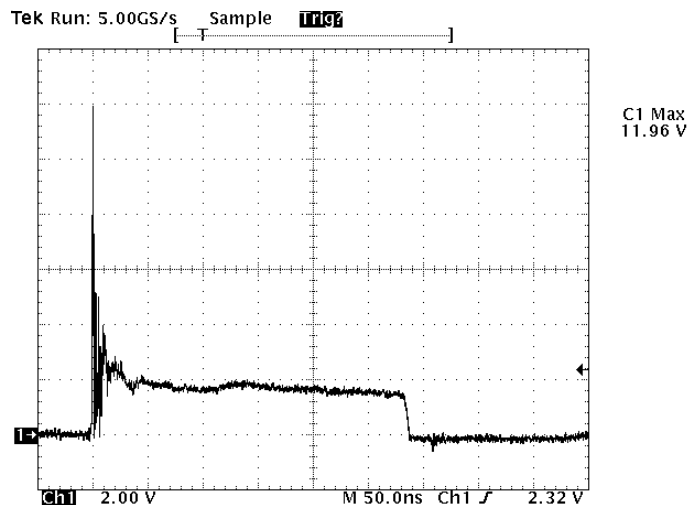
### Insertion Loss S21



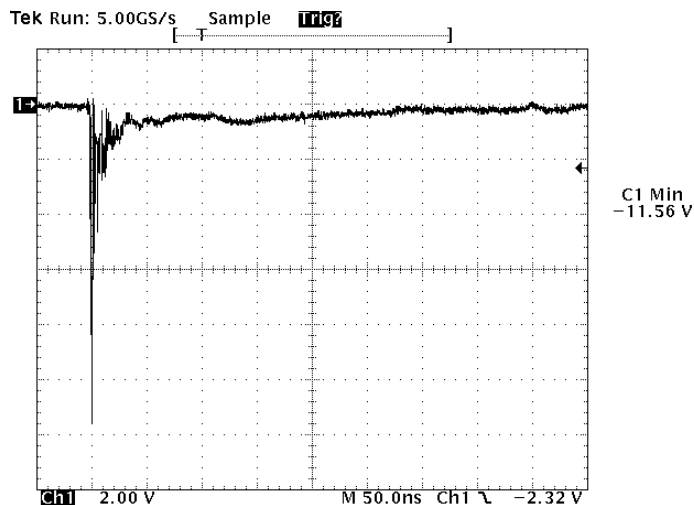
# PROTECTION PRODUCTS

## Typical Characteristics (Con't.)

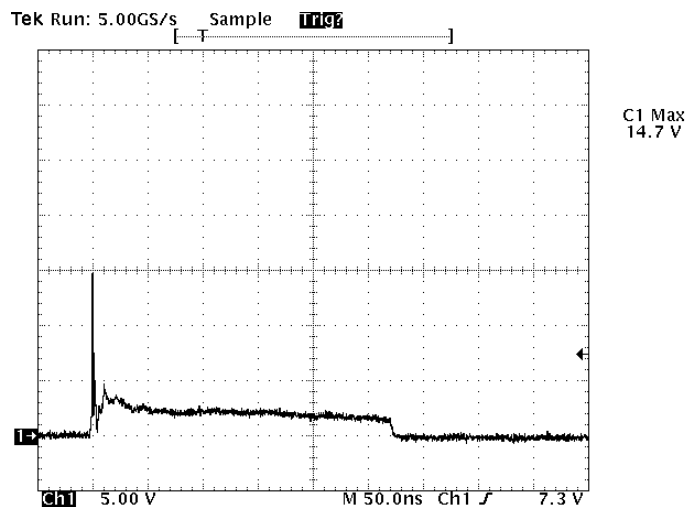
**ESD Clamping**  
(8kV Contact per IEC 61000-4-2)



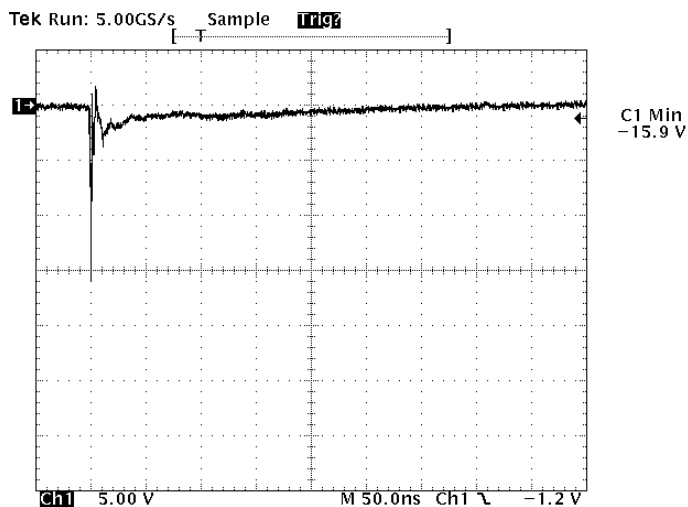
**ESD Clamping**  
(-8kV Contact per IEC 61000-4-2)



**ESD Clamping**  
(15kV air per IEC 61000-4-2)



**ESD Clamping**  
(-15kV air per IEC 61000-4-2)



## PROTECTION PRODUCTS

### Applications Information

#### Device Connection for Protection of Five Data Lines

These devices are designed to protect up to five unidirectional data lines. The device is connected as follows:

1. Unidirectional protection of five I/O lines is achieved by connecting pins 1, 3, 4, 5, and 6 to the data lines. Pin 2 is connected to ground. The ground connection should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces.

#### Circuit Board Layout Recommendations for Suppression of ESD.

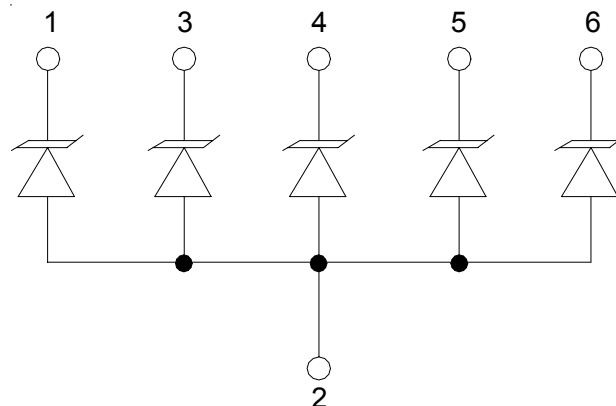
Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

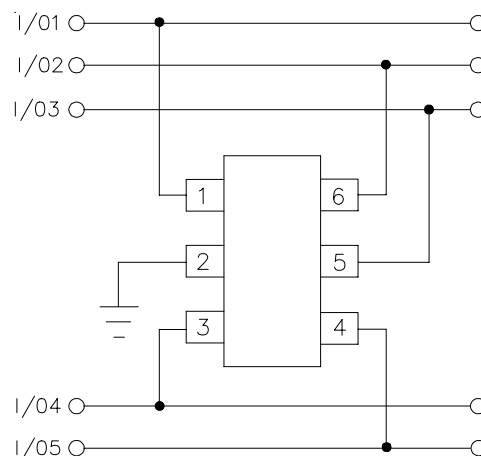
#### Matte Tin Lead Finish

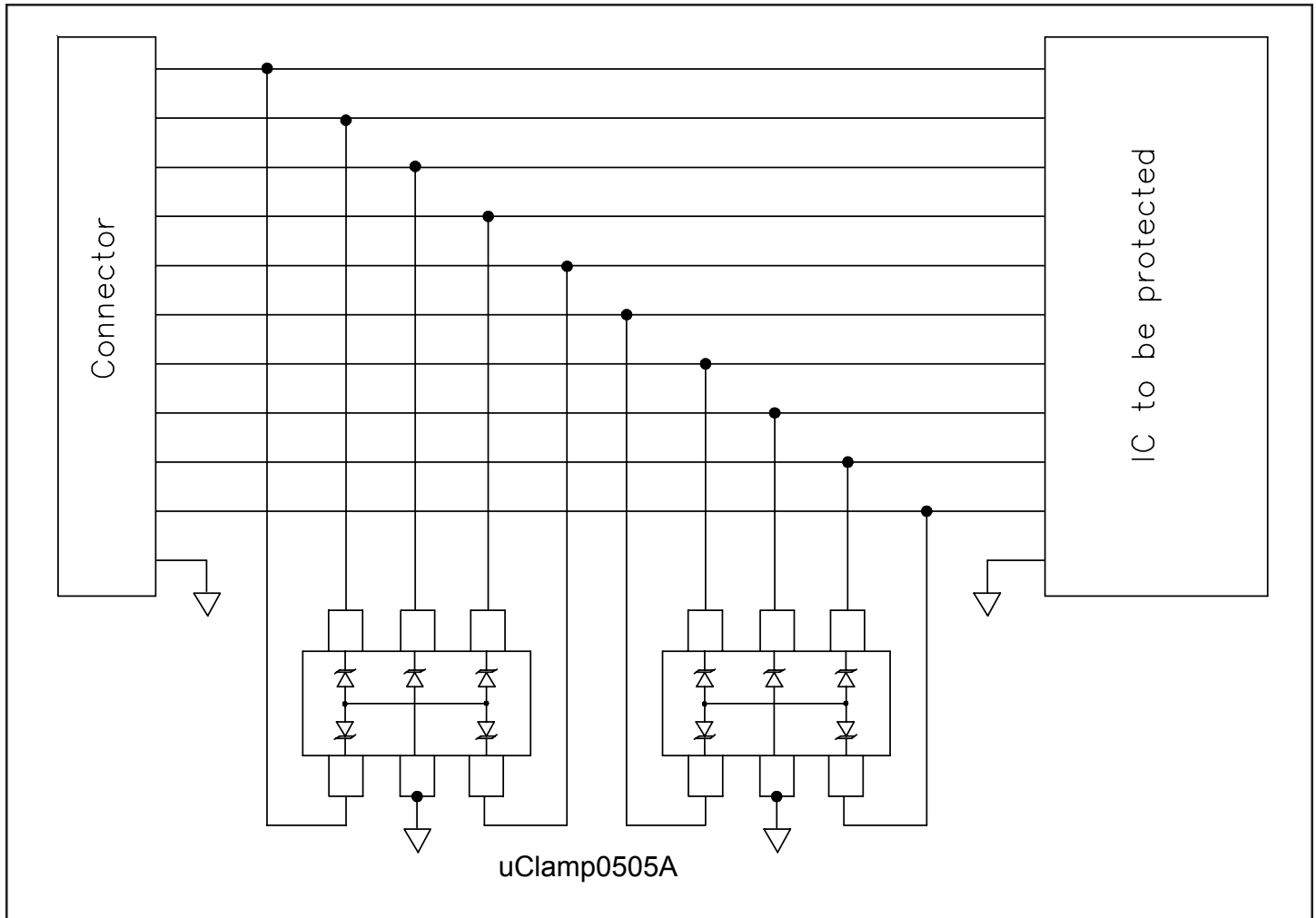
Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

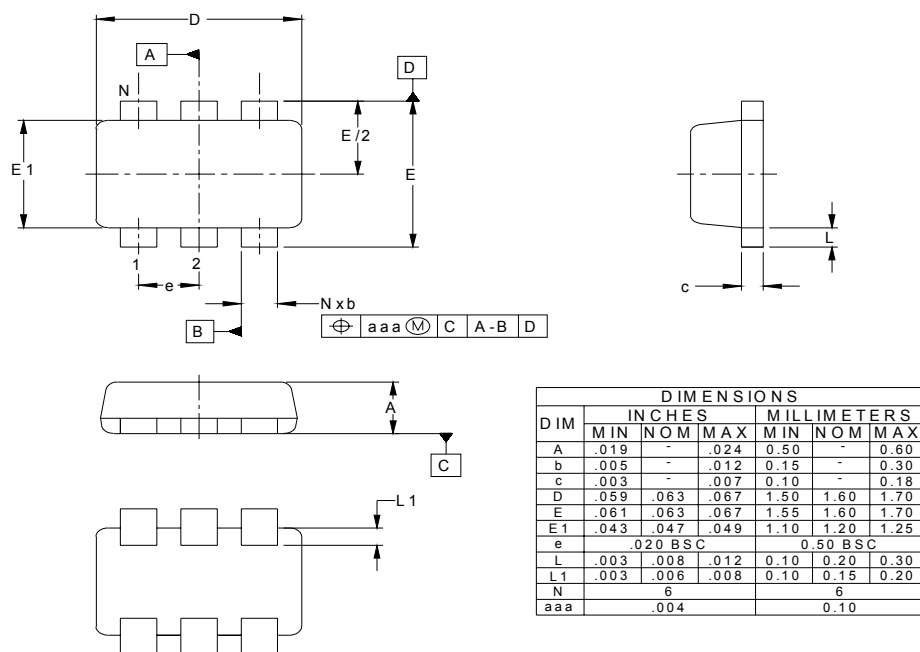
#### Circuit Diagram



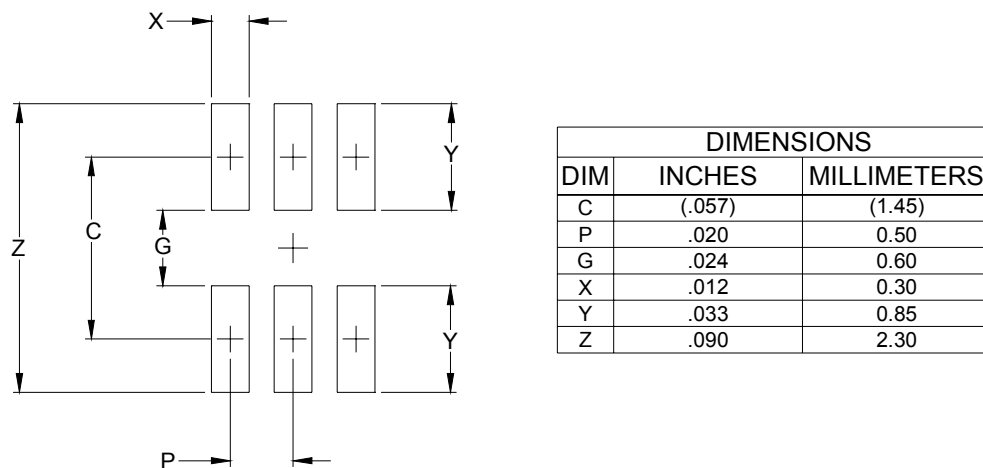
#### Protection of Five Unidirectional Lines



**PROTECTION PRODUCTS**
**Typical Applications**


**PROTECTION PRODUCTS**
**Outline Drawing - SC-89 (SOT-666)**

**NOTES:**

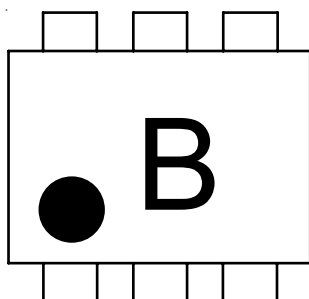
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. DIMENSIONS "E1" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

**Land Pattern - SC-89 (SOT-666)**

**NOTES:**

1. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY  
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR  
COMPANY'S MANUFACTURING GUIDELINES ARE MET.

## PROTECTION PRODUCTS

### Marking Code



### Ordering Information

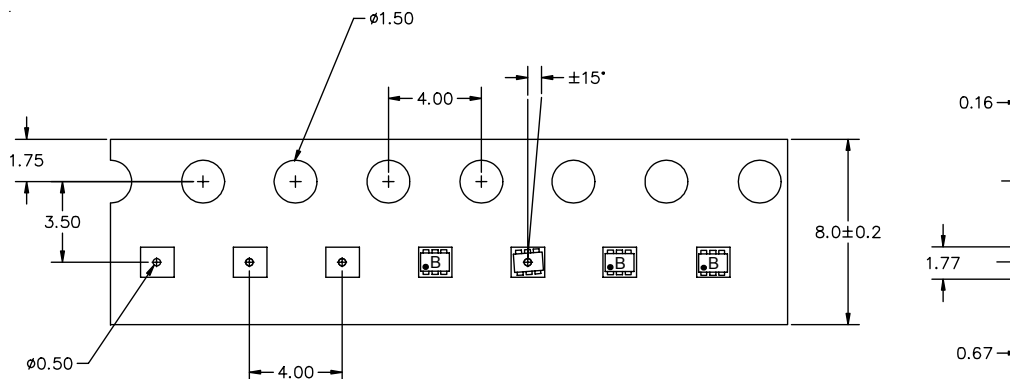
| Part Number     | Working Voltage | Device Marking | Qty per Reel | Reel Size |
|-----------------|-----------------|----------------|--------------|-----------|
| uClamp0505A.TCT | 5V              | B              | 3,000        | 7 Inch    |

MicroClamp, uClamp and  $\mu$ Clamp are trademarks of Semtech Corporation

Note:

- (1) Pin 1 Identified with a dot
- (2) Lead finish is matte tin

### Tape and Reel Specification



2 DIMENSIONS ARE IN MILLIMETERS.

1 SAME AS 3M US046041.

### Tape Specification and Device Orientation

### Contact Information

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